

# JMSH0401MGQ

## Product Summary

Parameters	Value	Unit
$V_{DSS}$	40	V
$V_{GS(th)\_Typ}$	2.7	V
$I_D(@V_{GS}=10V)$	223	A
$R_{DS(ON)\_Typ}(@V_{GS}=10V)$	1.4	m

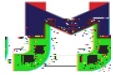
## Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMSH0401MGQ-13	SH0401MQ	1	Tape&Reel	PDFN5x6-8L	5000	50000

## Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-to-Source Voltage	40	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	A
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	Refer to Fig.4	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	459	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	W
$T_J$ STG			$^\circ\text{C}$

Symbol	Parameter	Max	Unit
$R_{JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	42	$^\circ\text{C/W}$
$R_{JC}$	Thermal Resistance, Junction to Case	1.0	

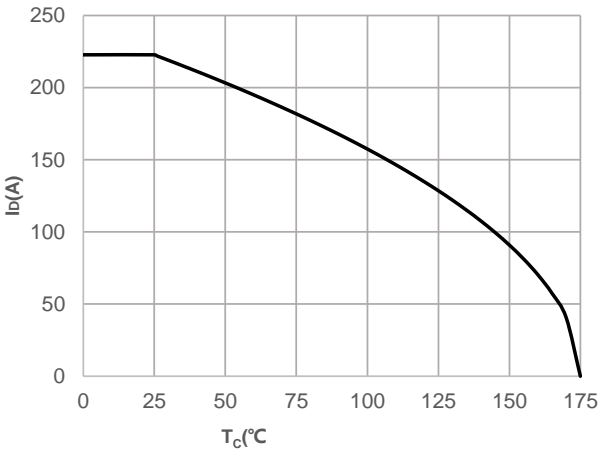
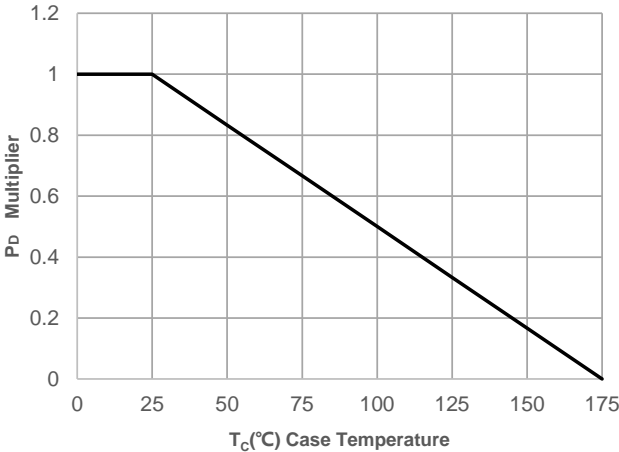
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

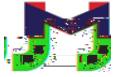
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\text{ A}, V_{GS} = 0\text{V}$	40	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 32\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ A}$	1.9	2.7	3.5	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance <sup>(4)</sup>	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	1.4	1.7	m
<b>Dynamic Characteristics</b>						
$R_g$	Gate Resistance	$f = 1\text{MHz}$	-	0.9	-	
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 20\text{V},$ $f = 1\text{MHz}$	2589	3625	4893	pF
$C_{oss}$	Output Capacitance		1413	1979	2671	pF
$C_{riss}$	Reverse Transfer Capacitance		113	158	213	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0\text{ to }10\text{V}$ $V_{DS} = 20\text{V}, I_D = 20\text{A}$	42	59	80	nC
$Q_{GS}$	Gate Source Charge		11	15	21	nC
$Q_{gd}$	Gate Drain("Miller") Charge		12	16	22	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 20\text{V}$ $I_D = 20\text{A}, R_{GEN} = 3$	-	16	-	ns
$t_r$	Turn-On Rise Time		-	29	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	35	-	ns
$t_f$	Turn-Off Fall Time		-	13	-	ns
<b>Body Diode Characteristics</b>						
$I_S$	Maximum Continuous Body Diode Forward Current		-	-	223	A
$I_{SM}$	Maximum Pulsed Body Diode Forward Current		-	-	891	A
$V_{SD}$	Body Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 20\text{A}$	-		1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F = 20\text{A}, di/dt = 100\text{A/us}$	37	52	70	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	66	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2.  $E_{AS}$  condition: Starting  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 20\text{V}$ ,  $V_{GS} = 10\text{V}$ ,  $R_G = 250\text{ohm}$ ,  $L = 3\text{mH}$ ,  $I_{AS} = 17.5\text{A}$ ,  $V_{DD} = 0\text{V}$  during time in avalanche.
  3.  $R_{JA}$  is measured with the device mounted on a  $1\text{inch}^2$  pad of 2oz copper FR4 PCB.
  4. Pulse Test: Pulse Width  $300\mu\text{s}$ , Duty Cycle  $0.5\%$ .

# Typical Performance Characteristics

Figure 1: Power De-rating





### Typical Performance Characteristics

Figure 5: Output Characteristics

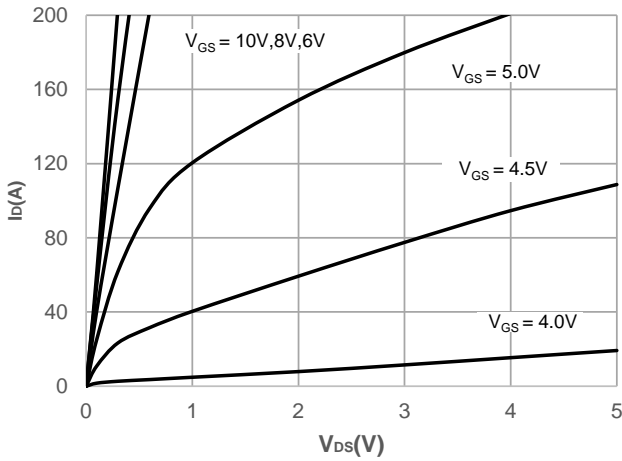


Figure 6: Typical Transfer Characteristics

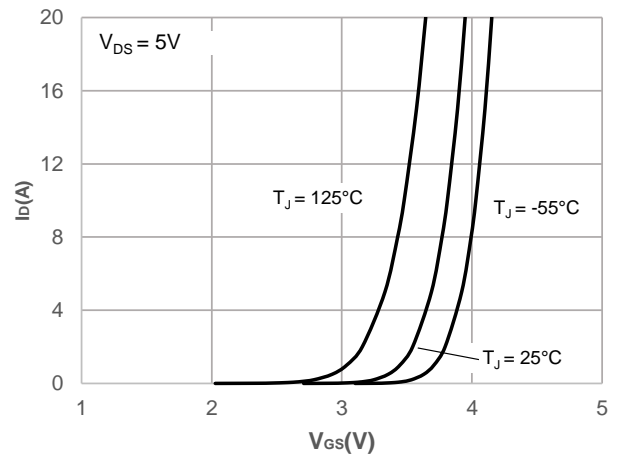


Figure 7: On-resistance vs. Drain Current

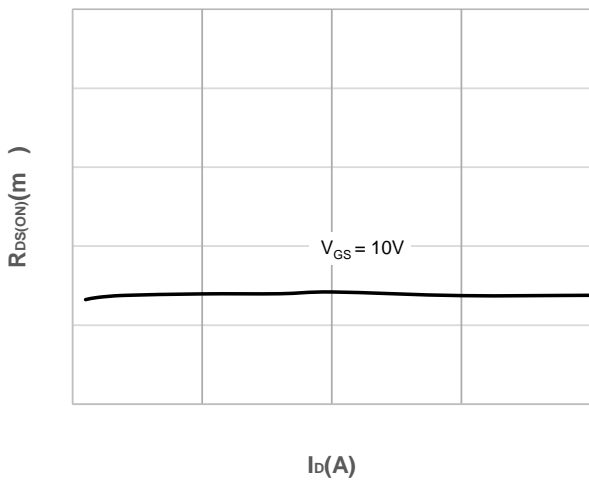


Figure 8: Body Diode Characteristics

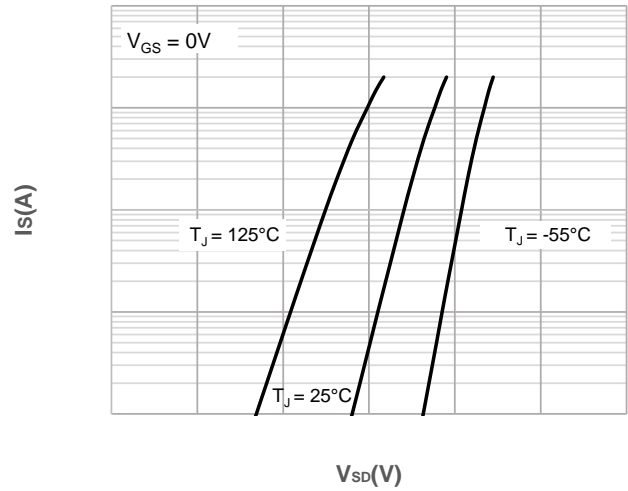


Figure 9: Gate Charge Characteristics

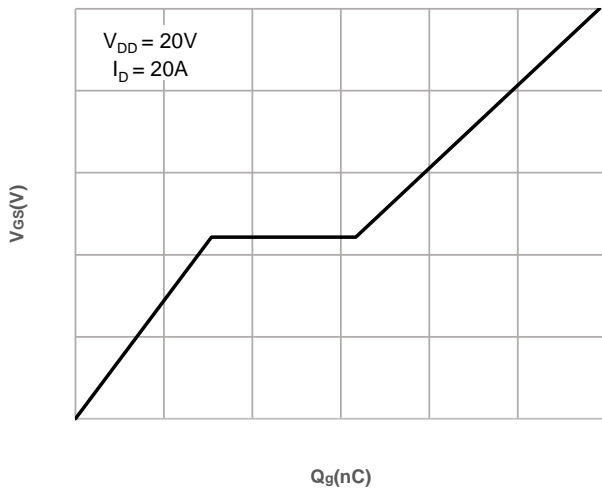
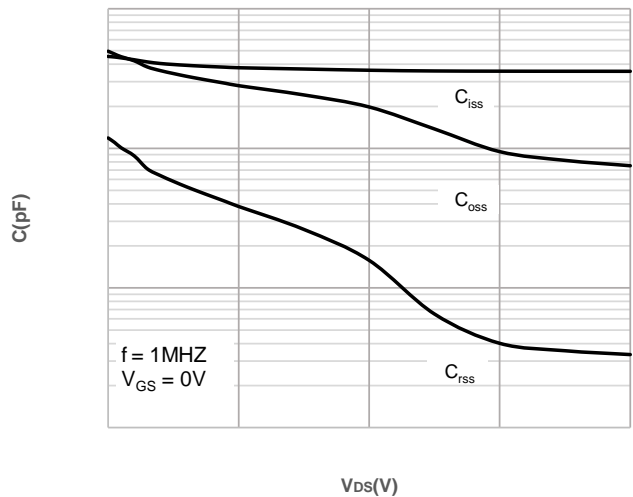


Figure 10: Capacitance Characteristics



### Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

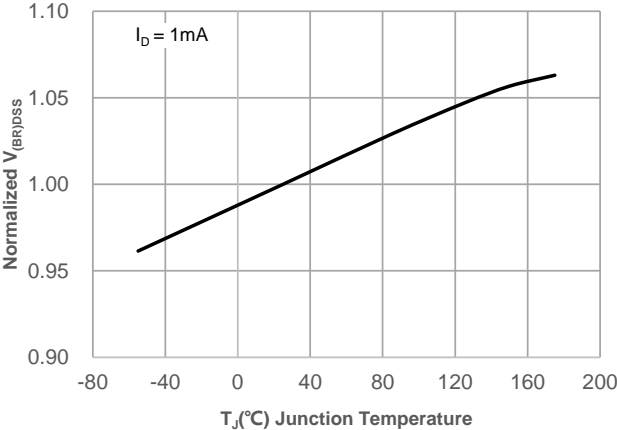


Figure 12: Normalized on Resistance vs. Junction Temperature

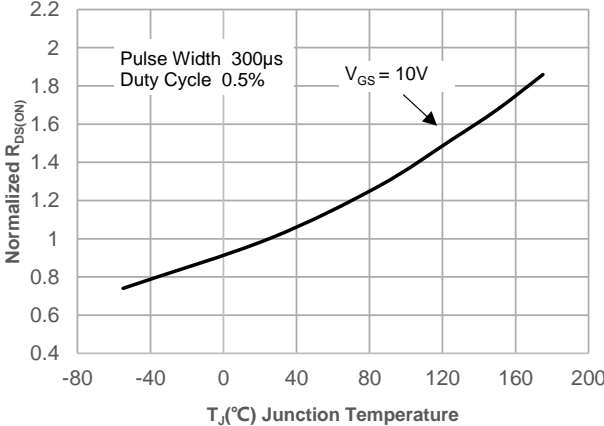
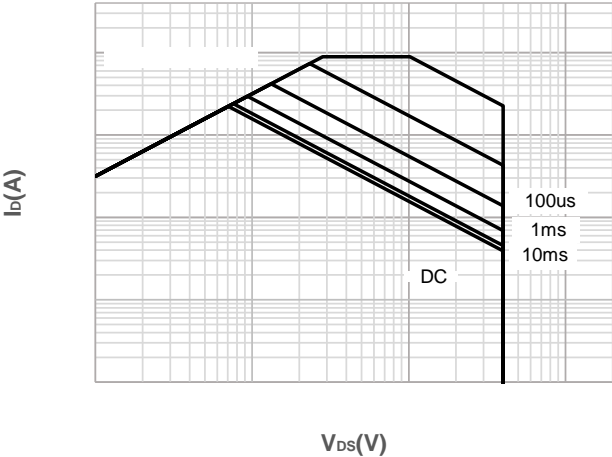


Figure 15: Maximum Safe Operating Area

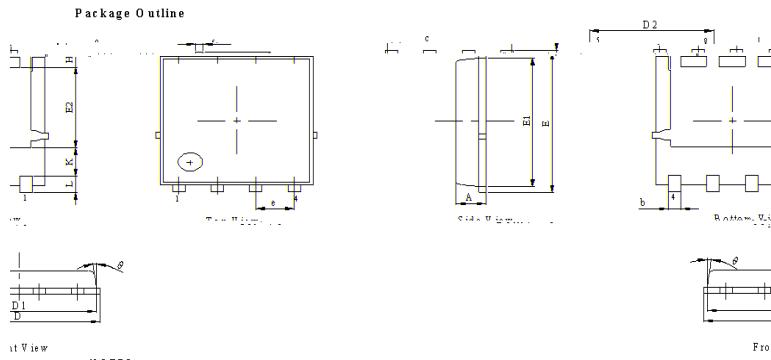


## Test Circuit

Figure 1: Gate



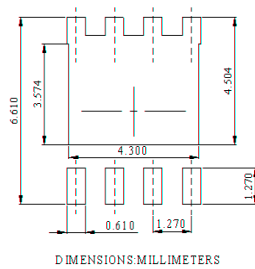
### Package Mechanical Data(PDFN5X6-8L)



- NOTES:
1. Dimension and tolerance per ASME Y14.5M, 1994.
  2. All dimensions in millimeter (angle in degree).
  3. Dimension D1 and D2 do not include mold flash.

MILLIMETER			
UNIT	MIN.	NOM.	MAX.
A	0.3	0	0.15
B	0.11	0.11	0.21
C	0.32	0.32	0.4
D1	4.95	5.05	5.15
D2	4	4.1	4.2
E	6.05	6.15	6.25
E1	5.5	5.6	5.7
H	0.6	0.6	0.8
I	0.6	0.6	0.8
L	1.25	1.25	1.5
R	0.05	0.05	0.1

Recommended Soldering Footprint



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